

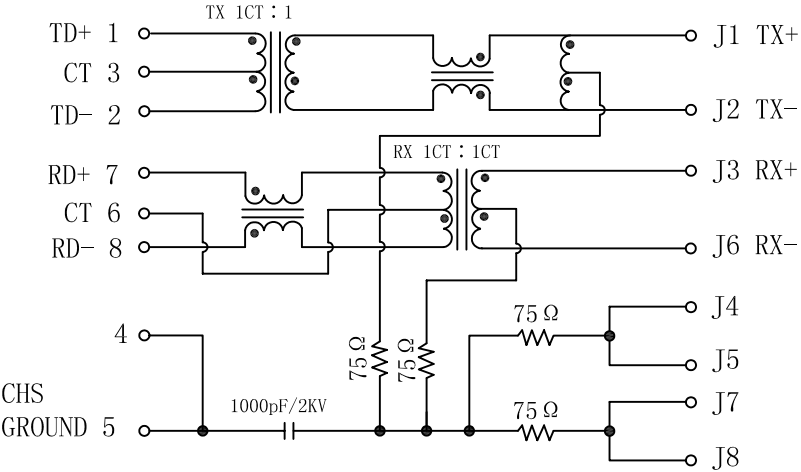
Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/27	

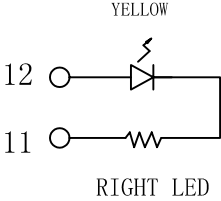
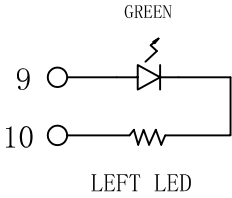
ELECTRICAL SPECIFICATIONS @25°C

1. Turn Ratio($\pm 2\%$):
TX=1CT : 1 RX=1CT : 1CT
2. Inductance OCL: 350uH MIN
@100KHz, 0.1V, 8mA DC Bias
3. Insertion Loss:
-1.0dB MAX @ 1-65MHz
4. Return Loss:
-20dB MIN @ 1-10MHz
-16dB MIN @ 10-30MHz
-12dB MIN @ 30-60MHz
-10dB MIN @ 60-100MHz
5. Cross talk:
-40dB MIN @ 1-30MHz
-35dB MIN @ 30-60MHz
-30dB MIN @ 60-100MHz
6. Common Mode Rejection:
-30dB MIN @ 1-50MHz
-20dB MIN @ 50-150MHz
7. Hipot Test: 1500Vrms MIN
8. Operating Temperature Range: 0°C TO 70°C.

PC BOARD CONNECTIONS



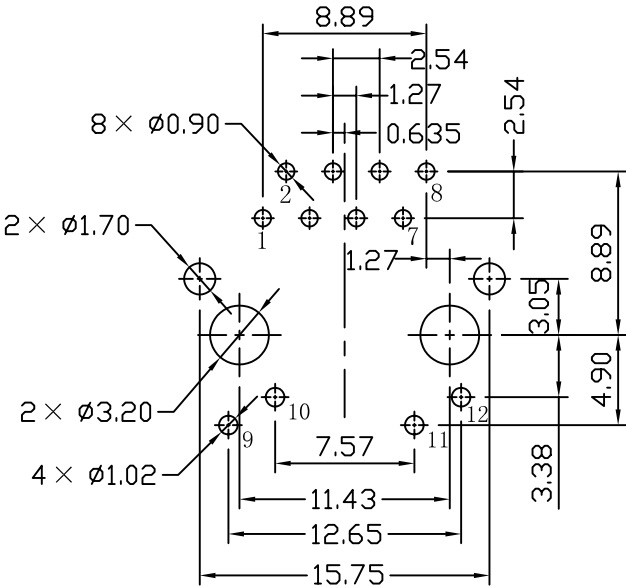
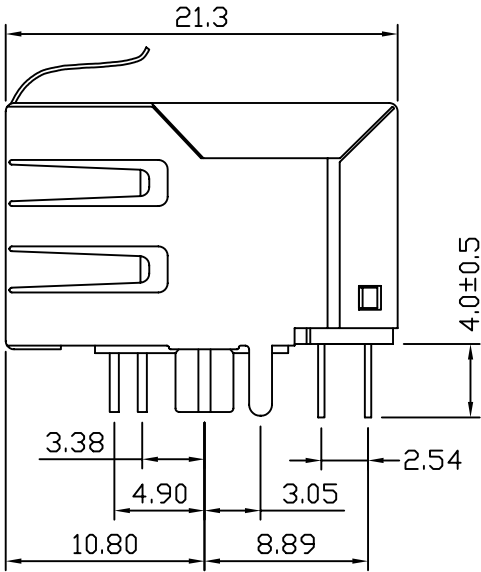
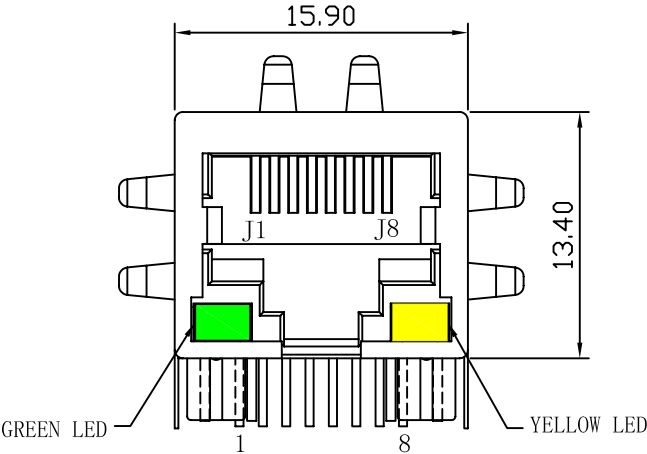
RJ45 CONNECTOR



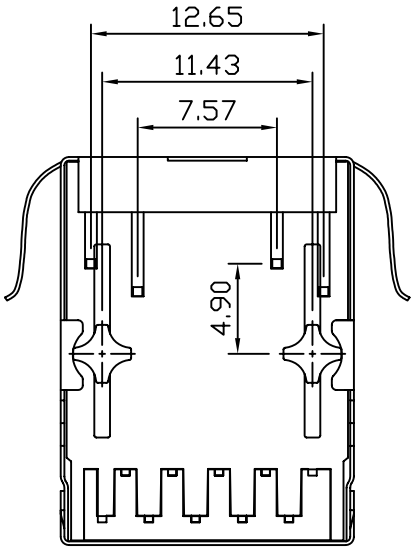
X:X	±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX	±0.05	DR: TOM		
ANGLES	±1°	UNIT: mm	PART NO. : LPJ0026A73NL	
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO. : LP10072702

Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/27	



SUGGESTED PCB LAYOUT (TOP VIEW)



- NOTES:
1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
 2. Meets IEEE 802.3 specification
 3. Connector Materials:
Housing: Thermoplastic UL94V-0
Contact/Shield: Copper alloy
Shield plating: Nickel
Contact plating: Gold 6 micro-inches min. In contact area.
 4. Wave solder tip temperature: 265°C Max
Wave solder tip temperature time: 5 Sec Max



X:X	±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX	±0.05	DR: TOM		
ANGLES	±1°	UNIT: mm	PART NO.: LPJ0026A73NL	
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO.: LP10072702